

2SD1267, 2SD1267A

Silicon NPN triple diffusion planar type

For power amplification

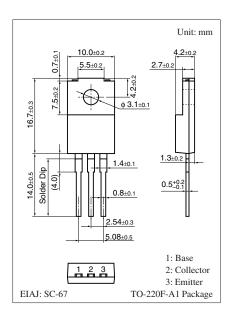
Complimentary to 2SB0942 and 2SB0942A

Features

- High forward current transfer ratio h_{FE} which has satisfactory linearity.
- Low collector-emitter saturation voltage V_{CE(sat)}
- Full-pack package which can be installed to the heat sink with one screw.

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage	2SD1267	V _{CBO}	60	V
(Emitter open)	2SD1267A		80	
Collector-emitter voltage	2SD1267	V _{CEO}	60	V
(Base open)	2SD1267A		80	
Emitter-base voltage (Col	V _{EBO}	5	V	
Collector current	I_{C}	4	A	
Peak collector current	I_{CP}	8	A	
Collector power	$T_C = 25^{\circ}C$	P _C	40	W
dissipation		2.0		
Junction temperature	T _j	150	°C	
Storage temperature	T_{stg}	-55 to +150	°C	



■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

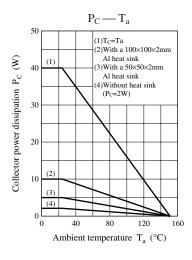
Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage	2SD1267	V _{CEO}	$I_C = 30 \text{ mA}, I_B = 0$	60			V
(Base open)	2SD1267A			80			
Base-emitter voltage		V_{BE}	$V_{CE} = 4 \text{ V}, I_{C} = 3 \text{ A}$			2	V
Collector-emitter cutoff	2SD1267	I _{CES}	$V_{CE} = 60 \text{ V}, V_{BE} = 0$			400	μΑ
current (E-B short)	2SD1267A		$V_{CE} = 80 \text{ V}, V_{BE} = 0$			400	
Collector-emitter	2SD1267	I_{CEO}	$V_{CE} = 30 \text{ V}, I_{B} = 0$			700	μΑ
cutoff current (Base open)	2SD1267A		$V_{CE} = 60 \text{ V}, I_{B} = 0$			700	
Emitter-base cutoff current (Collector open)		I_{EBO}	$V_{EB} = 5 \text{ V}, I_{C} = 0$			1	mA
Forward current transfer ratio		h _{FE1} *	$V_{CE} = 4 \text{ V}, I_{C} = 1 \text{ A}$	40		250	_
		h _{FE2}	$V_{CE} = 4 \text{ V}, I_{C} = 3 \text{ A}$	15			
Collector-emitter saturation voltage		V _{CE(sat)}	$I_C = 4 \text{ A}, I_B = 0.4 \text{ A}$			1.5	V
Transition frequency		f_T	$V_{CE} = 5 \text{ V}, I_{C} = 0.5 \text{ A}, f = 1 \text{ MHz}$		20		MHz
Turn-on time		t _{on}	$I_C = 4 \text{ A}, I_{B1} = 0.4 \text{ A}, I_{B2} = -0.4 \text{ mA}$		0.4		μs
Storage time		t _{stg}	$V_{CC} = 50 \text{ V}$		1.2		μs
Fall time		t _f			0.5		μs

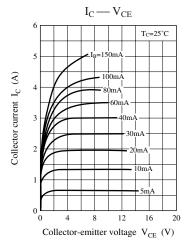
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

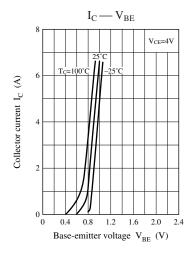
2. *: Rank classification

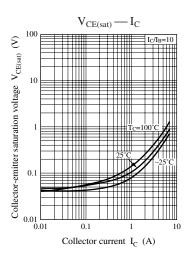
Rank	R	Q	Р
h_{FE1}	40 to 90	70 to 150	120 to 250

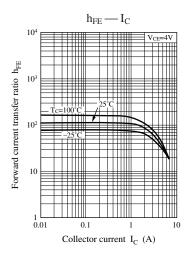
Panasonic

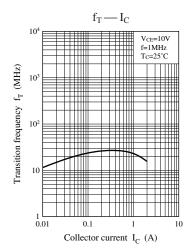


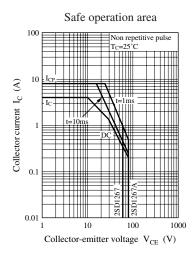


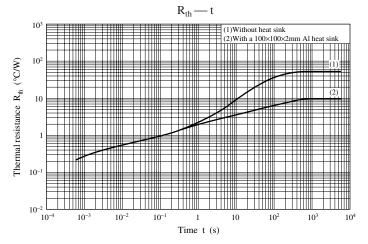












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